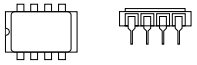
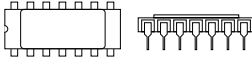
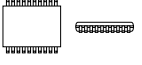
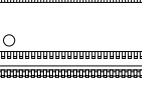
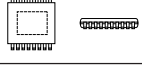


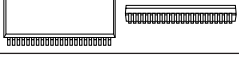
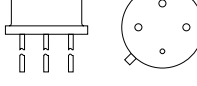
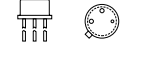

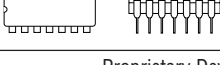
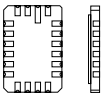
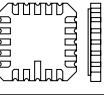





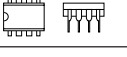
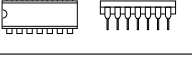
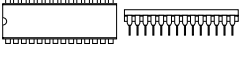
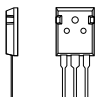
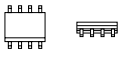
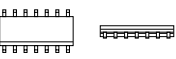
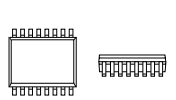
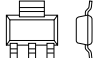

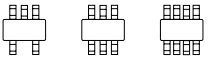



	PACKAGE OUTLINE*	DESCRIPTION	LTC	NSC	ADI	TI/BURR-BROWN	MAXIM
SIDE BRAZED		8-Lead Side Brazed (Hermetic)	D8	D	D	—	DA
		14-, 16-, 18- and 20-Lead Side Brazed (Hermetic)	D	D	D	—	DD, DE, DN, DP
TSSOP Thin Shrink Small Outline		14-, 20- and 28-Lead TSSOP (4.4mm)	F	MT	U	DL, PW	UP, UG, UI
		48- and 56-Lead TSSOP (6.1mm)	FW	MT	—	DGG	UM
		16-, 20- and 28-Lead TSSOP (4.4mm) Exposed Die Pad	FE	MH, MT	—	PWP	UP
SSOP Shrink Small Outline		16-, 20-, 24- and 28-Lead SSOP (Narrow 0.150)	GN	MQ	RS	DBQ	
		16-, 20-, 28- and 36-Lead Plastic SSOP (5.3mm)	G	MS	RS	DB	AP, AG, AT
		36- and 44-Lead SSOP (Wide 0.300)	GW	MS	—	DB	AX
METAL CANS		8- and 10-Lead TO-5 Metal Can	H	H	H	—	TV, TW, VS
		3- and 4-Lead TO-39 Metal Can	H	H	H	—	TV, TW, VS
		2-, 3- and 4-Lead Standard TO-46 Metal Can or in Thermal Caps	H	H	H	—	—
		3-Lead TO-52 Metal Can	H	—	—	—	SR
CERDIP Ceramic Dual-In-Line		8-Lead Ceramic DIP (Hermetic)	J8	J, J8	Q	JG	JA
		14- and 16-Lead Ceramic DIP (Narrow 0.300, Hermetic)	J	J, J14, J16	D, Q	J	RD, RN, RE, RP
Proprietary Device Prefixes			LT, LTC	LF, LP, LH, MF, LM	AD, OP, REF, CMP	TL	MAX

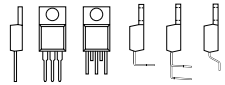
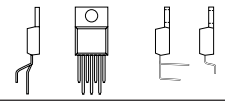
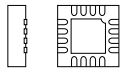
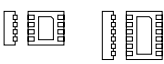
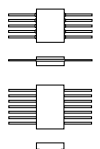
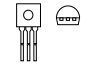
*Package Outlines Above Not to Scale

PACKAGE CROSS REFERENCE

	PACKAGE OUTLINE*	DESCRIPTION	LTC	NSC	ADI	TI/BURR-BROWN	MAXIM
LCC		20-Pin Leadless Chip Carrier (Rectangular, Hermetic)	L	E	E	FN, FK	L
		20-Pin Leadless Chip Carrier (Square 0.350, Hermetic)	LS	E	E	FN, FK	L
DD PAK		3-Lead DD Pak	M	S	—	—	—
		5-Lead DD Pak	Q	S	—	—	—
		7-Lead DD Pak	R	S	—	—	—
MSOP		8- and 10-Lead, Micro Small Outline Package (MSOP)	MS8, MS	MM	RM	DGK	UA, UB
		8- and 10-Lead Micro Small Outline Package (MSOP), Exposed Die Pad Option	MS8E, MSE	—	—	—	UA, UB
PDIP Plastic Dual-In-Line		8-Lead PDIP, Plastic Dual-In-Line	N8	N, N8	N	P	P
		14-, 16-, 18-, 20- and 24-Lead PDIP, Plastic Dual-In-Line (Narrow 0.300)	N	N, N14	N	N, NE	ND, NE, NN, NP, NG
		28-Lead PDIP, Plastic Dual-In-Line (Wide 0.600)	NW	—	N	N	PI
TO-3P (TO-247)		3-Lead TO-3P (Similar to TO-247)	P	—	—	—	K
SO Small Outline		8-Lead SO (Narrow 0.150)	S8	M	R	D	SA
		14- and 16-Lead Plastic SO (Narrow 0.150)	S	M	R	D	SD, SE
		16-, 18-, 20-, 24- and 28-Lead SO (Wide 0.300)	SW	M	R	D	WE, WN, WP, WF, WG, WI
SOT and SC70 Small Outline		3-Lead SOT-223 Small Outline Transistor	ST	MP	—	—	UR
		3-Lead SOT-23	S3,	M3	RT,	DBZ	UR, US
		5-, 6- and 8-Lead TSOT	S5, S6, TS8	M5, M6	UJ	DBV	UT, UK
		6- and 8-Lead SC70	SC6, SC8	MG	KS	DCK	XT
Proprietary Device Prefixes			LT, LTC	LF, LP, LH, MF, LM	AD, OP, REF, CMP	TL	MAX

*Package Outlines Above Not to Scale

PACKAGE CROSS REFERENCE

	PACKAGE OUTLINE*	DESCRIPTION	LTC	NSC	ADI	TI/BURR-BROWN	MAXIM
TO-220		3- and 5-Lead TO-220	T T	T T	— —	KC KV	C C
		7-Lead TO-220 (Formerly Y Package)	T7	—	—	KC	C
QFN Quad Flat No Lead		16- and 20-Lead QFN (3mm × 3mm)	UD	—	CP**	RGT	UD
		16-, 20-, 24- and 28-Lead QFN (4mm × 4mm)	UF	LQA	CP**	RGT, RGF	TE, TG
		20-, 24- and 28-Lead QFN (4mm × 5mm)	UFD	—	—	—	—
		32-Lead QFN (5mm × 5mm)	UH	—	—	RHB**	TJ
		38-Lead QFN (5mm × 7mm)	UHF	—	—	—	—
		40-Lead QFN (6mm × 6mm)	UJ	—	—	—	—
		48-Lead QFN (7mm × 7mm)	UK	—	CP**	RGZ**	TM
		56-Lead QFN (5mm × 9mm)	UHH	—	—	—	—
		52-Lead QFN (7mm × 8mm)	UKG	—	—	—	—
64-Lead QFN (9mm × 9mm)	UP	—	CP**	RTD**	—		
DFN Dual Flat No Lead		8-, 10- and 12-Lead DFN (3mm × 3mm)	DD	—	CP**	DRB, DRC	TA
		8-, 10- and 12-Lead DFN (3mm × 2mm)	DDB	—	CP**	—	—
		3-, 4-, 6- and 8-Lead DFN (2mm × 2mm)	DC	—	—	—	—
		6- and 8-Lead DFN (2mm × 3mm)	DCB	—	—	—	—
		12-Lead DFN (4mm × 3mm)	UE	—	—	—	—
		12- and 14-Lead DFN (4mm × 3mm)	DE	—	—	—	—
		16-Lead DFN (5mm × 5mm)	DH	—	—	—	—
		16-Lead DFN (5mm × 3mm)	DHC	—	—	—	—
		16-Lead DFN (5mm × 4mm)	DHD	—	—	—	—
22-Lead DFN (6mm × 3mm)	DJC	—	—	—	—		
FLATPAK		10- and 14-Lead Flatpak, Glass Sealed (Hermetic)	W	W	L	UO10	FB
		10- and 14-Lead Flatpak, Metal Sealed, Bottom Brazed (Hermetic)	WB	F	AH-148, LM	WO10, WO14	M
TO-92		3-Lead, TO-92 Package	Z	Z	—	LP	ZR
Proprietary Device Prefixes			LT, LTC	LF, LP LH, MF LM	AD, OP, REF, CMP	TL	MAX

*Package Outlines Above Not to Scale

**Closest Package, Comparable Footprint, Higher Height